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form: A4mmXLc	 2.PLATING AS TABLE SHOW. 3.SEE GS-12-148 FOR PRODUCT SPECIFICATION. 4.SEE GS-14-551 AND GS-14-816 FOR PACKAGING SPECIFICATION. 5.PACKING OPTION 3: "CUSTOMER-SPECIFIC PACKAGING; LIMITED TO CERTAIN SIZES." PACKING OPTION 2: "NOT ALL SIZES ARE AVAILABLE; CHECK WITH FACTORY" 6.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN (7)THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 (8) PLATING OPTION '4' IS LEADFREE ALTERNATIVE FOR OPTION '0', AND OPTION '6' IS LEADFREE ALTERNATIVE FOR OPTION '1'. 9 THIS PARTNUMBER IS ONLY CATER FOR SPECIAL CUSTOMER REQUIREMENT OF COPLANARITY OF 0.1 FOR ALL POSITION. 	10069524- NUMBER OF POSITIONS 12 2 X30 14	Copyright FCL.
_	ion. CKAGING SPECIFICATION. ACKAGING; LIMITED TO CERTAIN SIZES." ALABLE; CHECK WITH FACTORY" SSURE TO 260°C PEAK A CONVECTION, INFRA-RED OR A CONVECTION, INFRA-RED OR A DIRECTIVES AND OTHER COUNTRY -008 A DIRECTIVES AND OTHER COUNTRY -008 SPECIAL CUSTOMER REQUIREMENT OF	Image: set of the set of th	1 2 FClconnect.com
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-	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	J PACKAGING PACKAGING 0 1 POLARIZATION PEG 1 POLARIZATION PEG 1 PLATING ON CONTACT AREA 0 GOLD 0.2 um MIN. / TIN LEAD SOLDER 1 WITH GOLD FLASH (0.1 um MIN.) / TIN LEAD SOLDER 2 GOLD 0.2 um MIN. / TIN LEAD SOLDER 1 WITH GOLD FLASH (0.1 um MIN.) / TIN LEAD SOLDER 4 GOLD 0.38um MIN. / MATT PURE TIN ON SOLDER TAIL (LEAD FREE PLATING) 5 GOLD 0.38um MIN. / MATT PURE TIN ON SOLDER TAIL (LEAD FREE PLATING) 6 WITH COLD FLASH (0.1 um MIN.) / MATT PURE TIN SOLDER TAIL (LEAD FREE PLATING) 6 WITH COLD FLASH (0.1 um MIN.) / MATT PURE TIN SOLDER 6 WITH COLD FLASH (0.1 um MIN.) / MATT PURE TIN SOLDER	ω
4	mily BERGSTAK 1 BOARD TO BOARD 1ACLE ASS'Y 0069524 CUSTOMER Drawing CUSTOMER Drawing B	LF (note 7&8.) PDM: Rev:B STATUS:Released Printed: Dec 03,	() + 2009









